

## **LISTING OF CLAIMS**

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Previously Presented) A process for the production of a film having at least one electrical component, in particular of organic semiconductor technology, wherein an adhesive layer comprising a radiation-cross-linkable adhesive is applied to a base film, the adhesive layer of the radiation-cross-linkable adhesive is applied in a form structured in pattern form to the base film and/or is irradiated in the form of a pattern in such a way that the adhesive layer hardens structured in a pattern form, a transfer film which comprises a carrier film and an electrical functional layer is applied to the adhesive layer with an orientation of the electrical functional layer to the adhesive layer, and the carrier film is removed from the film body including the base film, the adhesive layer and the electrical functional layer, wherein in a first region which is structured in pattern form the electrical functional layer remains as part of the electrical component on the adhesive layer and on the base film and in a second region which is structured in pattern form the electrical functional layer remains on the carrier film and is removed with the carrier film from the base film, wherein the adhesive layer comprising a radiation-cross-linkable adhesive is irradiated in pattern form after application of the transfer film, whereby the adhesive layer hardens in a region structured in pattern form, and the carrier film is removed from the film body including the base film, the adhesive layer and the electrical functional layer, so that the electrical functional layer remains on the base film in the first region which is structured in pattern form and in which the adhesive layer is hardened and is removed with the carrier film in the second region in which the adhesive layer is not hardened.

2. (Previously Presented) A process for the production of a film having at least one electrical component, in particular of organic semiconductor technology, wherein an adhesive layer comprising a radiation-cross-linkable adhesive is applied to a base film, the adhesive layer is applied in a form structured in pattern form to the base film and/or is irradiated

in the form of a pattern in such a way that the adhesive layer hardens structured in a pattern form, a transfer film which comprises a carrier film and an electrical functional layer is applied to the adhesive layer with an orientation of the electrical functional layer to the adhesive layer and the carrier film is removed from the film body including the base film, the adhesive layer and the electrical functional layer, wherein in a first region which is structured in pattern form the electrical functional layer remains as part of the electrical component on the adhesive layer and on the base film and in a second region which is structured in pattern form the electrical functional layer remains on the carrier film and is removed with the carrier film from the base film, wherein the adhesive layer comprising the radiation-cross-linkable adhesive is irradiated in pattern form prior to the application of the transfer film in such a way that the adhesive layer hardens in a region structured in pattern form, the transfer film is applied to the adhesive layer which is hardened structured in pattern form and the carrier film is removed from the film body including the base film, the adhesive layer and the electrical functional layer, so that the electrical functional layer remains on the base film in the first region which is structured in pattern form and in which the adhesive layer is not hardened and is removed with the carrier film in the second region which is structured in pattern form and in which the adhesive layer is hardened.

3. (Previously Presented) A process according to claim 1, wherein the adhesive layer comprising the radiation-cross-linkable adhesive is applied to the base film by means of a printing process with structuring in pattern form.

4. (Previously Presented) A process according to claim 1, wherein the adhesive layer is printed on to the base film by means of intaglio printing.

5. (Previously Presented) A process according to claim 1, wherein the adhesive layer is printed on to the base film by means of offset printing or flexoprinting.

6. (Previously Presented) A process according to claim 3, wherein the transfer film is radiation-transparent and the adhesive layer is exposed from the side of the transfer film through the transfer film.

7. (Previously Presented) A process according to claim 3, wherein the base film is radiation-transparent and the adhesive layer is exposed from the side of the base film through the base film.

8. (Previously Presented) A process according to claim 1, wherein a radiation-cross-linkable adhesive is used, which in the non-hardened condition has a lower adhesion force with respect to the electrical functional layer than the adhesion force between the electrical functional layer and the carrier film.

9. (Previously Presented) A process according to claim 2, wherein the adhesive layer is then irradiated in a second exposure step for hardening the regions of the adhesive layer, which are not yet hardened.

10. (Previously Presented) A process according to claim 1, wherein a mask exposure device, in particular a drum exposure device or a mask exposure device with a mask belt is used for the exposure operation.

11. (Previously Presented) A process according to claim 1, wherein a transfer film is used, which has a release layer between the carrier film and the electrical functional layer.

12. (Previously Presented) A process according to claim 1, wherein the electrical functional layer is an electrically conductive layer.

13. (Previously Presented) A process according to claim 12, wherein the electrical functional layer contains conductive nanoparticles, in particular metal, carbon black or graphite particles.

14. (Previously Presented) A process according to claim 13, wherein the electrical functional layer comprises conductive nanoparticles and binding agent.

15. (Previously Presented) A process according to claim 13, wherein the electrical functional layer is compressed upon being applied to the base film, whereby the electrical conductivity of the functional layer is increased.

16. (Previously Presented) A process according to claim 12, wherein the electrical functional layer contains conductive polymers.

17. (Previously Presented) A process according to claim 12, wherein the electrical functional layer contains inorganic substances, for example ITO material.

18. (Previously Presented) A process according to claim 12, wherein the electrical functional layer is a metal layer or a layer of a metal alloy.

19. (Previously Presented) A process according to claim 1, wherein the electrical functional layer is an electrical semiconducting layer which has in particular semiconducting polymers.

20. (Previously Presented) A process according to claim 1, wherein the adhesive layer comprises an electrically non-conductive adhesive.

21. (Previously Presented) A process according to claim 1, wherein the adhesive layer comprises an electrically conductive adhesive.

22. (Withdrawn) A film produced by a process according to claim 1, having at least one electrical component, in particular of organic semiconductor technology,

wherein the film has an adhesive layer comprising a radiation-cross-linkable adhesive and the adhesive layer is arranged between an electrical functional layer structured in pattern form and a base film of the film and joins the electrical functional layer structured in pattern form to the base film.

23. (Withdrawn) A film according to claim 22, wherein the adhesive layer of a radiation-cross-linkable adhesive is structured in pattern form in the same way as the electrical functional layer structured in pattern form.

24. (Withdrawn) A film according to claim 22, wherein the electrical functional layer is a microstructured electrode layer providing one or more electrodes of the electrical component.

25. (Withdrawn) A film according to claim 22, wherein the electrical functional layer is a microstructured semiconductor layer providing one or more semiconducting component parts of the electrical component.

26. (Withdrawn) A film according to claim 22, wherein the electrical component is an organic field effect transistor.

27. (Canceled)

28. (Canceled)